

Title (en)
METHOD FOR TESTING PRINTED CIRCUIT BOARDS

Title (de)
VERFAHREN ZUM PRÜFEN VON LEITERPLATTEN

Title (fr)
PROCÉDÉ D'ESSAI DE PLAQUETTES À CIRCUIT IMPRIMÉ

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Abstract (en)
[origin: WO2010081834A1] The invention relates to a method for testing printed circuit boards by means of a test apparatus which has a test arrangement for making contact with printed circuit board test points on a printed circuit board to be tested. The test arrangement has test contact elements in a predetermined, regular grid. The method comprises the following steps: a) pressing the test arrangement onto the printed circuit board to be tested in a first test position with respect to the printed circuit board to be tested, such that a plurality of printed circuit board test points may contact with at least one test contact element, b) measurement of a plurality of conductor tracks for interruptions and short circuit by means of continuity measurements, c) movement of the test arrangement with respect to the printed circuit board to be tested, to a further test position in which at least one printed circuit board test point made on a conductor track makes contact with at least one test contact element, which conductor track has not yet previously been completely measured for interruption and short circuit, e) repetition of steps c) and d) until at least the plurality of conductor tracks on the printed circuit board to be tested has been measured, wherein the test arrangement is used, the test contact elements of which are arranged with a density of at least one hundred contact points per square centimetre.

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